



PCFAB LINE CARD

Please visit our website at www.floridacirtech.com for MSDS and technical bulletins.

FINAL FINISHES

IMMERSION SILVER FINISH

PC5012	Soak cleaner made from a concentrated blend of acids & surfactants. Removes oils, fingerprints, and other organics.
CirEtch 130	Sulfuric / peroxide microetch which promotes a bright silver finish.
IS 150	Immersion silver bath that plates a bright, uniform, solderable silver finish.
IS 127	An optional cleaner. Halide free, biodegradable, non-hazardous acid cleaner designed to remove copper oxides and mild silver tarnish.
IS 175	An anti-tarnish bath for silver. A good option if tarnish is an issue.
STR 199	Silver tarnish remover. Removes tarnish and restores solderability.

ELECTROLESS NICKEL IMMERSION GOLD (ENIG)

PC 300:	Acidic soak cleaner for ENIG.
CT 300:	Palladium catalyst for ENIG.
EN 300:	Electroless nickel bath, with good stability and solderability.
IG 300:	Immersion gold bath, protects the solderability of the nickel.
NS 41:	Nickel strip solution used for rework. Leaves the copper bright and shiny.

LEAD FREE HOT AIR LEVELING (LF HASL)

Florida CirTech offers a Tin-Copper-Nickel alloy that is superior for lead free HASL.

SN100CL:	Lead – Free solder for HASL. SN100CL is a tin-copper-nickel alloy.
SN100CLe:	Lead – Free solder replenisher for HASL. SN100CLe is a tin-nickel alloy.
HARAJ65A:	High viscosity flux with a wide operating window. It has good thermal stability for lead-free applications.

ELECTROLESS COPPER SYSTEMS

PERMANGANATE ETCH BACK / DESMEAR

EB 610:	Solvent conditioner swells and softens the resins.
EB 613:	Potassium permanganate etchant dissolves the resins.
EB 660:	Acidic neutralizer which eliminates residual permanganate.
GE 77:	Glass etch power. This is added to the EB 660 neutralizer bath when glass etching is desired.

CLEANERS / CONDITIONERS

CC 106:	Strong alkaline, cationic cleaner conditioner which is a good all-around product. CC106 does not contain alkyl phenols.
CC 108:	Strong alkaline, cationic cleaner conditioner which is a good all-around product.
CC 110:	Alkaline cleaner - conditioner with excellent rinse-ability. Slightly lower activity than CC 108.

CATALYSIS

PD 140C: Powder pre-dip salts. Also used to makeup CT 164.
CT 164: Low-acid, palladium-tin catalyst used for electroless copper deposition.
AC 177: Sulfuric acid based accelerator, used after CT 164.

ELECTROLESS COPPER

EC 200: Highly stable, low deposition bath that plates 1 micro inch per minute at 80 F.
EC 74: Medium deposition bath that plates 2 - 3 micro inches per minute at 80 F.
EC 82: Medium to high deposition bath that plates 2.5 – 3.5 micro inches per minute at 105 F.
ECR: Electroless Copper Reducer, which is a stabilized formaldehyde blend.

OXIDE REPLACEMENT – POWER BOND

PB 405: Alkaline cleaner for Power Bond. Removes resist residues and other organic contamination.
PB 406: Acidic cleaner for Power Bond based on sulfuric and phosphoric acids. Removes oxides and conversion coatings.
PB 433: Pre-dip for Power Bond which enhances uniformity of the coating. Also used as an adhesion promoter for dry film and solder mask.
PB 445: Power Bond bath which is an alternative to brown / black oxides. Power Bond is based on a sulfuric / peroxide microetch and deposits a dark brown coating.
PBO: Power Bond Oxidizer. Stabilized 50% hydrogen peroxide solution.

DIRECT METALLIZATION – OMEGA II PROCESS

OMEGA II is a direct metallization system based on palladium and copper. It plates a copper web with sufficient conductivity to facilitate subsequent electrolytic copper plating. OMEGA II is a replacement for electroless copper.

CC 131: Cleaner conditioner for the OMEGA II process.
PD 155: Liquid pre dip for OMEGA II, used before the CT 160 catalyst.
CT 160: Palladium / tin catalyst used for OMEGA II direct metallization.
AC 171: Accelerator for OMEGA II direct metallization.

DEVELOPER CHEMISTRIES

DV 200: 40% potassium carbonate solution. DV 200 contains ingredients to keep equipment clean.
DV 205: Buffered 40% potassium carbonate solution, with cleaning agents. Good all around developer.
DV 215: Concentrated developer regenerator solution. Used along with DV205 or ACT 2070.
ACT 2070: 35% potassium carbonate solution which contains our most potent cleaning agents.

ELECTROLYTIC PLATING CHEMISTRY

ACID CLEANERS

PC 5009: Citric and phosphoric acid blend soak cleaner.
PC 5012: Highly concentrated soak cleaner. This cleaner does not contain alkyl phenols.

ELECTROLYTIC COPPER PLATING ADDITIVES

CP 155: Bright finish, one part, acid copper additive.
CP 157: Bright finish, one part, acid copper additive.

ELECTROLYTIC TIN AND SOLDER PLATING ADDITIVES

SP 130: Acid tin additive, used for tin etch resists.
SP 201: Additive that works well for both tin and tin / lead solder.
SP 201M: Concentrated additive to makeup a SP 201 bath.

STRIP CHEMISTRIES

PHOTORESIST STRIPPERS

RS 3001:	MEA based resist stripper. Good all-around stripper.
RS 3150:	Semi-aqueous resist stripper. Also used to strip fully cured solder mask.
RS 5000:	Caustic based resist stripper for innerlayer stripping.
RS 5002:	Modified caustic based stripper for small particle size and low cost.
RS 6040:	Our fastest resist stripper based on MEA and ethylene diamine.

TIN and SOLDER STRIPPERS

SSA & SSB:	Nitric acid based first step of the SS A / B and SS 2 two step solder stripper.
SS 2:	Ferric chloride based second step of the SS A / B and SS 2 two step system.
SS 3:	Ferric chloride based copper cleaner used before solder mask or HASL.
SS 200 or SS 280:	One step peroxide based solder stripper with high capacity, for spray applications.
EZ 5050:	One step nitric acid / ferric nitrate based solder stripper for conveyORIZED machines. This is a good all-around stripper.
EZ 6001:	A vertical batch treatment stripper, with low copper attack and added fume suppressants.
EZ 7001:	Concentrated replenisher for EZ 5050 conveyORIZED solder stripper.

SOLDER MASK AND INKS

We distribute SANWA Chemical solder masks and inks. SANWA inks come in a variety of colors and textures for screen-printing, and spray applications.

SOLDER MASK LPI

SPSR-950 LC-1:	LC-1 series was developed for fine solder dams. Good all around LPI.
SPSR-950 C-20:	C-20 series has excellent chemical resistance, for use with immersion tin, ENIG, etc.

ETCH RESISTS AND INKS

SM-530:	Thermal curable marking ink.
UR-3100:	UV curable solder mask.
MUV-1000:	UV curable marking ink.
UE-9000:	UV curable etch resist.

SCREEN CLEANERS

SC 3:	Biodegradable, ester based, slow evaporating screen cleaner. Good all around cleaner.
SC 4:	Similar to the SC3 screen cleaner with orange oil for increased solvency.
SC 5:	Glycol ether-ester blend, slow evaporating screen cleaner with excellent solvency.
SC 15:	Glycol ether, ester, orange oil blend, slow evaporating screen cleaner.
SC 9:	A novel water based screen cleaner. More effective than DBE based products.

HOT AIR SOLDER LEVELING

HOT AIR SOLDER LEVELING

HA 290:	Low viscosity flux with glycol ether added for improved wetting. Good for vertical applications.
HA 300:	Low viscosity flux. Widely used for tight tolerance boards.
HA 305:	Medium viscosity flux. Especially suited for vertical Lantronic machines.
HA 1010:	High viscosity, general-purpose flux for vertical machines.
HA 1030T:	Excellent horizontal HASL flux. Reduces the amount of sludge/charring build up.
HARAJ65A:	High viscosity flux with a wide operating window. Good for Argus & Quicksilver machines.
RA 2000:	Rinse aid that dramatically decreases ionic contamination as well as neutralizes the board after hot air leveling, fusing or immersion tin applications.
WS 220:	Excellent solder dross blanket for horizontal HASL machines.

METALS

- NITRO-FLO PLUS: High purity 63 / 37 bar solder. Cast under nitrogen to eliminate oxides.
NITRO-FLO TIN: High purity tin bar used for solder adjustment in HASL processes.
SN100CL: Lead-free solder for start-up of HASL machines. SN100CL is a tin-copper-nickel alloy.
SN100CLe: Lead-free solder replenisher for HASL. SN100CLe is a tin-nickel alloy.

MISCELLANEOUS PRODUCTS

ACID CLEANERS

- CB 709: Tri-acid cleaner, based on sulfuric, nitric, and phosphoric acids, with copper antitarnish agents. Good for use as an inner layer core cleaner.
CB 710: Acid cleaner based on sulfuric and phosphoric acids. Recommended for use as a cleaner prior to outer layer imaging.
PC 5009: Citric and phosphoric acid blend soak cleaner.
PC 5012: Highly concentrated soak cleaner. This cleaner does not contain alkyl phenols.

ANTI-TARNISH FOR COPPER

- AT 701: Acidic, benzotriazole based anti-tarnish for copper.

BROWN / BLACK OXIDE

- MC 5011: Alkaline cleaner for brown / black oxide treatment
MT 80: Traditional brown / black oxide treatment

COPPER MICRO ETCHANTS

- CirEtch 100: Powdered monopersulfate based microetch. Longer life and more stability than either ammonium or sodium persulfate based micro-etches.
CirEtch 130: Hydrogen peroxide and sulfuric acid microetch.
CirEtch 200: Monopersulfate & sulfuric acid based microetch in liquid form.

DE-FOAMERS (BUBBLE BUSTER)

- BB 200: Non-silicone based defoamer. Ideal for rinse systems following the reflow process.
BB 300: Block copolymer based defoamer designed for developers and strippers.
BB 330: Economical version of BB 300.

EQUIPMENT CLEANERS

- EC 2: Our most concentrated equipment cleaner for longest life and re-usability.
ECA: Equipment cleaner additive used in addition to EC2 to remove solder mask residues from solder mask developers.

SOLDER MASK STRIPPERS

- RS 3150: Glycol ether based fully cured solder mask stripper. Also used as a semi-aqueous resist stripper.

SOLDER REFLOW AND FUSING CHEMISTRIES

- SB 100: Standard solder brightener used prior to reflow.
RF 450: Non-foaming I.R fusing flux that offers excellent laminate protection and consistent surface smoothness.
HO 351: Non-flammable glycol ether based flux for tin-lead reflow. Contains no alcohol.
WS 210: A non-foaming reflow fluid with excellent rinse-ability.
WS 215: A quenching fluid that is completely water soluble and low foaming.
WS 220: High thermal stability reflow fluid with exceptionally long life.
WS 250: High viscosity reflow fluid. Excellent for large ground planes where de-wetting may be a problem.

WASTE TREATMENT CHEMISTRIES – FCT WATER

Florida CirTech offers a complete line of waste treatment chemistries through our affiliate FCT Water Treatment. Visit www.fctwater.com for details.

ASSEMBLY PRODUCTS – FCT ASSEMBLY

Florida CirTech offers a complete line of assembly products including stencils, solder paste, fluxes, wire solder, and bar solder. Assembly products are sold through our affiliate FCT Assembly. Contact us at 970-346-8002 or visit www.fctassembly.com for details.